



Electronics Materials Information

| 2017-18

TEHCET's Critical Materials Report on CMP Consumables -Pads & Slurry

Supply Chain and Materials Market Analysis

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ACKNOWLEDGEMENTS

Thank you to all who provided input for this year's report. Most of those that participated wish to remain anonymous. They included all major channel suppliers in addition to larger end users. Other information for this report was gleaned from industry conferences, technical experts and literature in the public domain.

RESEARCH METHODOLOGY

TEHCET employs subject matter experts having first-hand experience within the industries which they analyze. Most of TEHCET's analysts have over 25 years of direct and relevant experience in their field. Our analysts survey the commercial and technical staff of IC manufacturers and their suppliers, and conduct extensive research of literature and commerce statistics to ascertain the current and future market environment and global supply risks. Combining this data with TEHCET's proprietary, quantitative wafer forecast results in a viable long-term market forecast for a variety of process materials.

READERS' NOTE

This report represents the interpretation and analysis of information generally available to the public or released by responsible agencies or individuals. Data was obtained from sources considered reliable. However, accuracy or completeness is not guaranteed.

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